



## Product/Process Change Notice

PCN # P-2005-0002

Date: 2020/05/18

Dear Customer:

Please be informed that Macronix is going to add 2nd source assembly subcontractor to backup customer original approved assembly subcontractors for 16 SOP(300mil) package products. The 2nd source assembly subcontractor is LINGSEN.

The detailed information about this change is described in the following pages. This process change has passed Macronix' qualification based on JEDEC standard, and the qualification report is attached below.

If you have any questions, concerns, or requests about this change, please contact your local Macronix Sales Representatives within 30 days, otherwise Macronix will assume customer received the PCN with no comments and the change is acceptable to the customer. Macronix follows JEDEC J-STD-046, it stipulates: ".....Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".

Thank you.

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(Note: For the customers who receive Macronix PCNs via distributors, Macronix will assist the distributors to convey the PCNs to the customers. It is each distributor's responsibility to communicate and track the responses of each customers and report back to Macronix, the distributor shall assume full responsibilities if failed to do so.)

**PCN No.:** P-2005-0002**Issue Date :** 2020/05/18**Subject:** Adding a new assembly vendor—LINGSEN for 16 SOP(300mil) package products.**Affected Macronix Part No.:**

MX25LM51245GMI00

MX25U51245GMI00

MX25U51291GMI40

MX25UM51245GMI00

**Package type:** 16 SOP(300mil) package products**Change Category :** New assembly vendor**Reason of Change:**

Due to COVID-19 pandemic induced community lockdown and L/F material shortage in Malaysia, which affected the assembly site ASECL, in order to ensure a smooth supply chain, add a new assembly site --LINGSEN, to avoid shortage and to increase production flexibility.

**Before Change :**

Assembly vendor:

1. ASECL

**After Change :**

Assembly vendors:

1. ASECL
2. LINGSEN

**Product identification:**

ASECL assembled IC the marking has vendor code: X

LINGSEN assembled IC the marking has vendor code: L

**Assessment of Change:**

1. No impact to Form, Fit, Function, Quality & Reliability.
2. LINGSEN assembled 16 SOP(300mil) package has passed Macronix' qualification based on JEDEC MSL level 3 standards, and it is also Halogen-Free, and meets the RoHS standards..
  - \* Attached is LINGSEN assembled 16 SOP(300mil) package qualification report.
3. LINGSEN has been one of Macronix' qualified assembly vendors with good quality for a long time.

**Schedule:**

Sample available date: 2020/6/30

1st shipping date: 2020/8/15 (Or follow PCN agreement with the customer)



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## **LINGSEN 16 SOP(300mil) Package Qualification Report**

### **1. PURPOSE:**

To qualify the new assembly subcontractor “LINGSEN” for 16 SOP(300mil) package.

### **2. PACKAGE PROFILE:**

ASSEMBLY HOUSE	LINGSEN
PACKAGE	16 SOP(300mil)
DIE SIZE	6532 x 5208 $\mu m^2$
DIE ATTACH	HITACHI HR-9004
LEAD FRAME	Copper, Double Ring Silver
WIRE BOND MATERIAL	Au
MOLD COMPOUND	Sumitomo G700
LEAD FINISH	Matte Sn

### **3. QUALIFICATION ITEMS, TEST CONDITION AND FLOW:**

#### **3-1. QUALIFICATION ITEMS:**

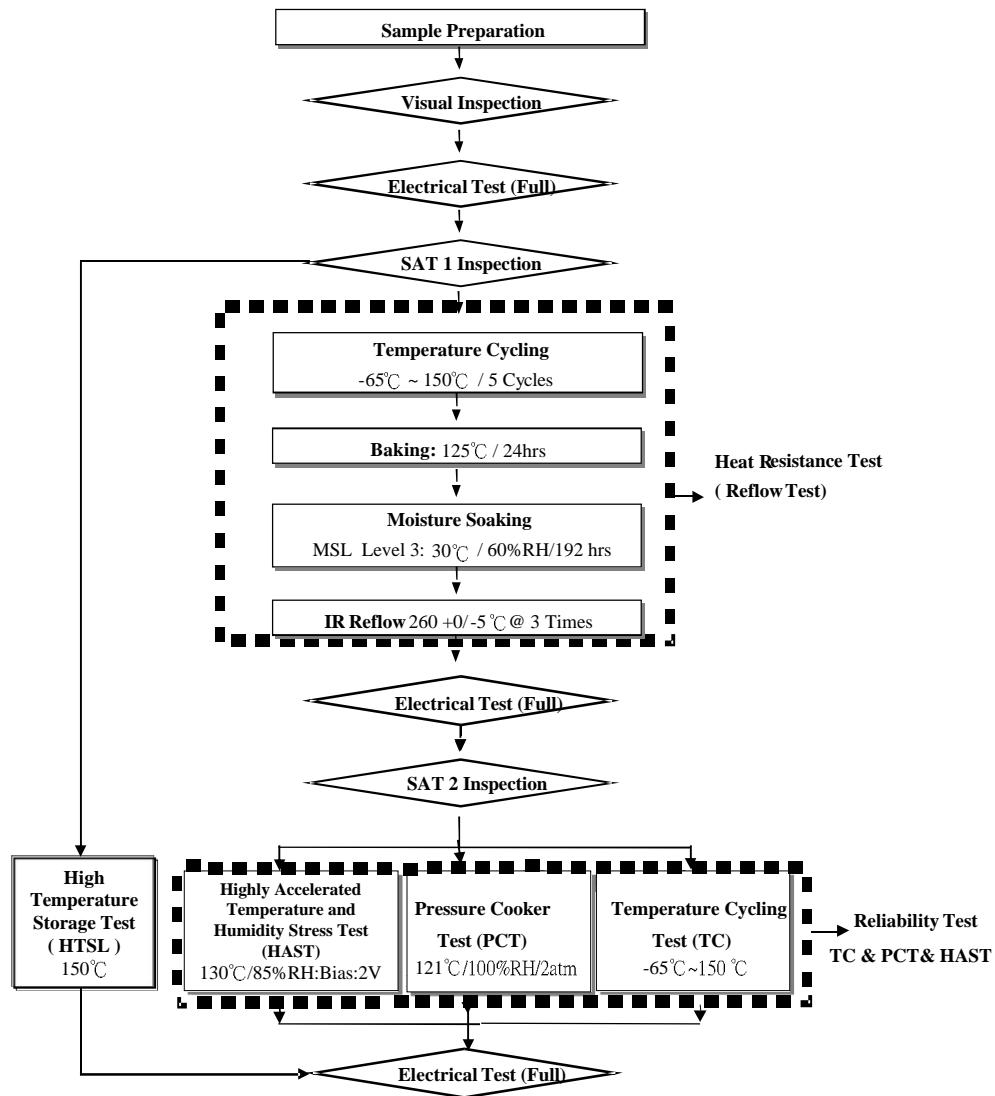
Test Item	Reference	Test Condition
1. Heat Resistance Test: Reflow Test	JEDEC J-STD-020	MSL: Follow JEDEC MSL Level 3 (30°C/ 60%RH, 192hrs)
2. Pressure Cooker Test	JESD22-A102	121°C/ 100%RH/ 2atm
3. Temperature Cycling Test	JESD22-A104	-65°C ~150°C
4. Highly Accelerated Temperature and Humidity Stress Test	JESD22-A110	130°C/ 85% RH, Bias: 2.0V
5. High Temperature Storage Life Test	JESD22-A103	150°C
6. Solderability Test	JESD22-B102	■ Steam aging 8hrs & Dipping Time $\leq$ 5sec ■ Sn-Ag-Cu solder paste: 245°C ■ Sn-Pb solder paste: 235°C

\*Perform SAT examination before and after Preconditioning per JESD22-A112.



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### 3-2. HEAT RESISTANT TEST (REFLOW TEST) AND RELIABILITY TEST FLOW

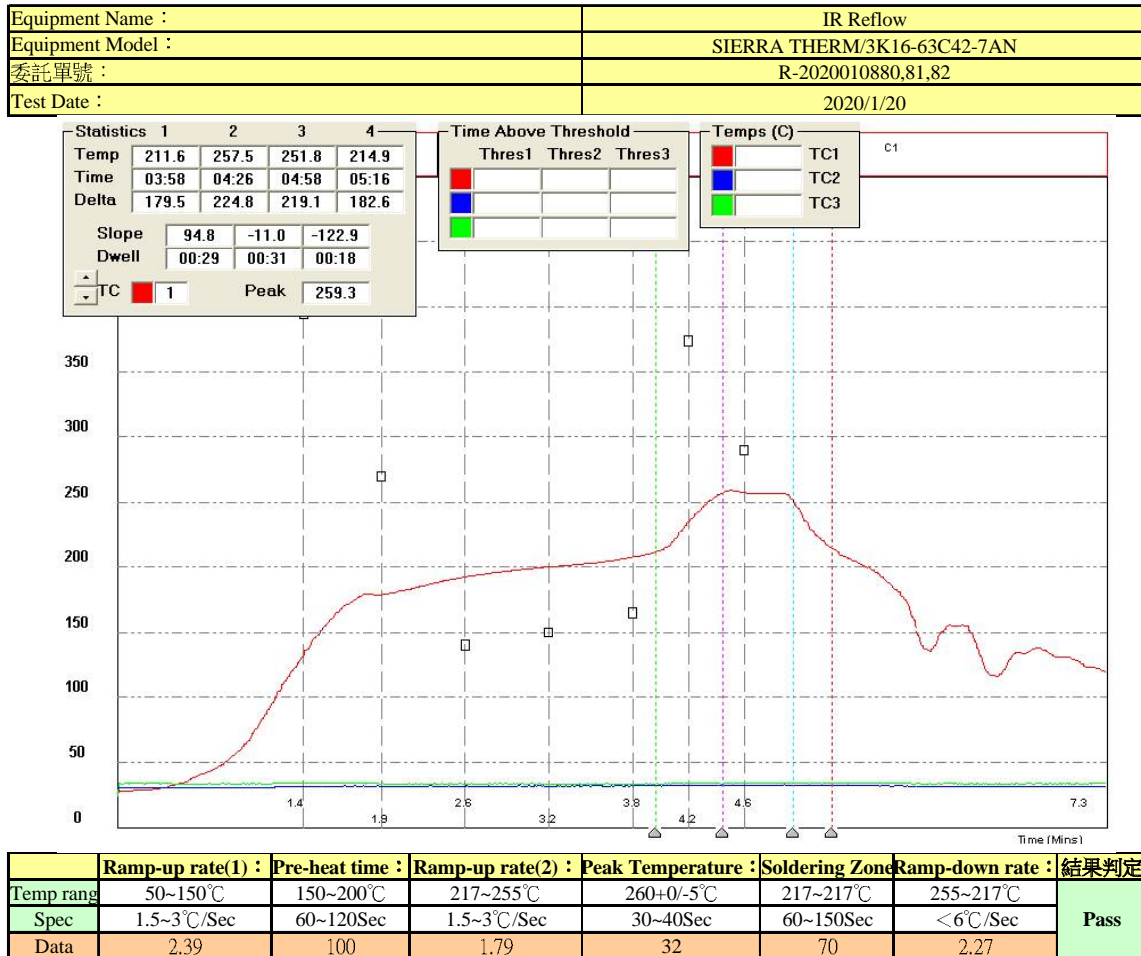




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### 3-2-1. REFLOW PROFILE:

**Ra Lab Reflow Test Data**



Note 1: Subject the samples to 3 cycles of the above defined reflow conditions

Note 2: Time 25°C to peak temperature: 8 minutes max.

Note 3: The time between reflows shall be 5 minutes minimum and 40 minutes maximum.

### 3-2-2. CRITERIA:

LTPD= 3%, PCT 96 hours and TC 500 cycles & HAST 96 hours & HTSL 500 hours.

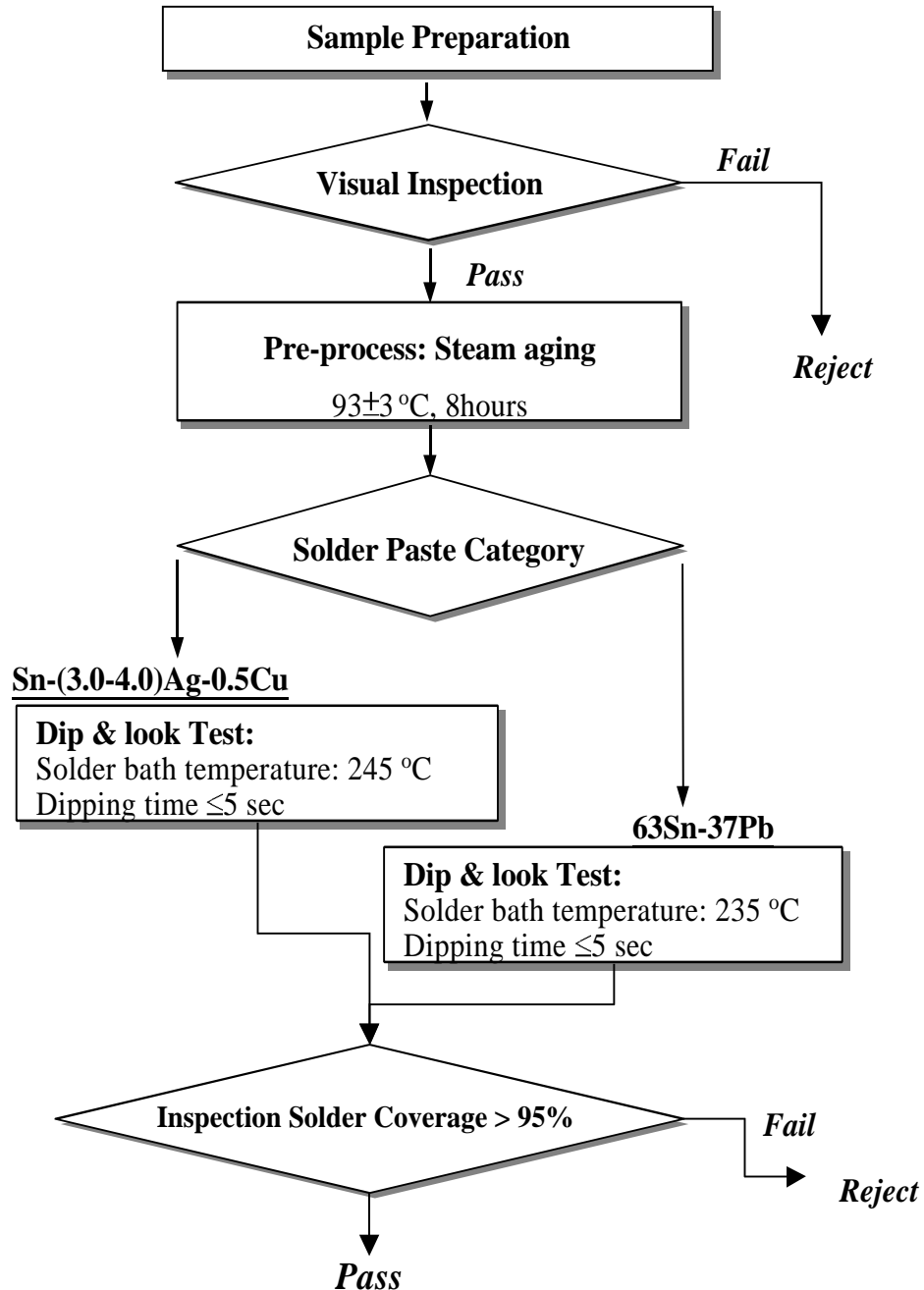
### 3-2-3. REFERENCE SPECIFICATION:

5650-0901: ASSEMBLY RELIABILITY QUALIFICATION SPEC



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### 3-3. SOLDERABILITY TEST FLOW





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#### 4. RESULTS:

##### 4-1. HEAT RESISTANCE TEST and RELIABILITY TEST RESULTS:

PRODUCT	6732		
LOT#	8F806400BD	8F806400BH	8F806400BK
DATE CODE	L1950	L1950	L1951
SAT 1	0/22	0/22	0/22
PRECON	0/231	0/231	0/231
SAT 2	0/22	0/22	0/22
PCT 96 HRS	0/77	0/77	0/77
TC 500 CYC	0/77	0/77	0/77
HAST 96 HRS	0/77	0/77	0/77
HTSL 500 HRS	0/45	0/45	0/45

**FAIL / SAMPLE SIZE**

##### 4-2. SOLDERABILITY TEST RESULTS:

###### Matte Sn Plating

Plating Material	Matte Sn		
Solder Paste Material	Sn-(3.0-4.0)Ag-0.5Cu		
INSPECTION	0/5	0/5	0/5

**FAIL / SAMPLE SIZE**

Plating Material	Matte Sn		
Solder Paste Material	63Sn-37Pb		
INSPECTION	0/5	0/5	0/5

**FAIL / SAMPLE SIZE**

#### 5. CONCLUSION: PASS

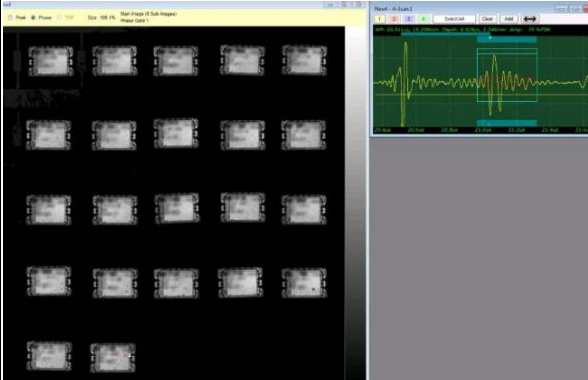
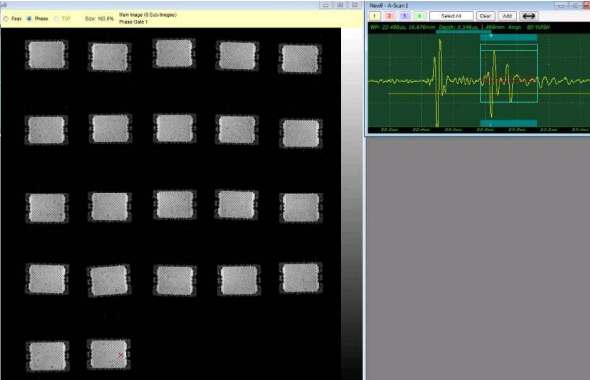
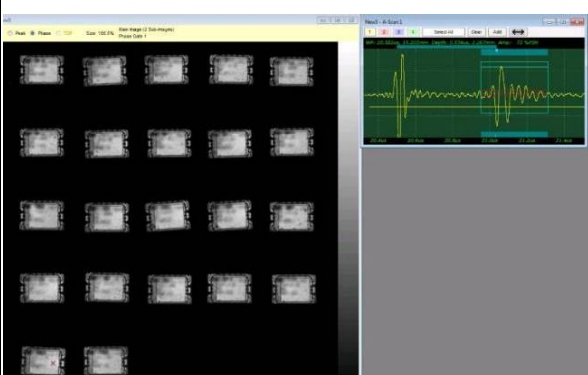
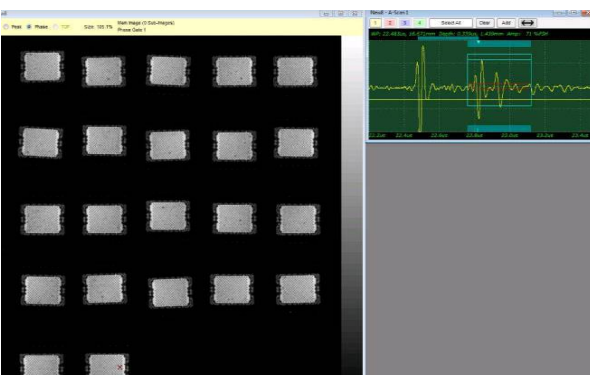
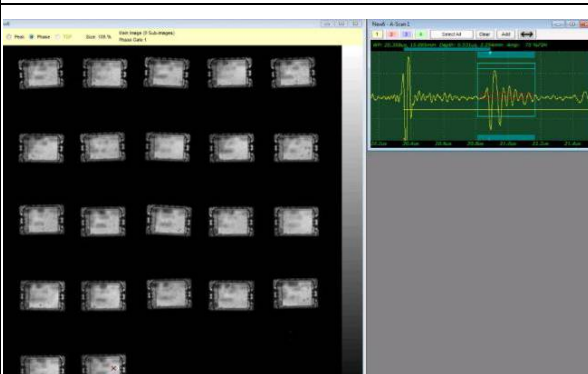
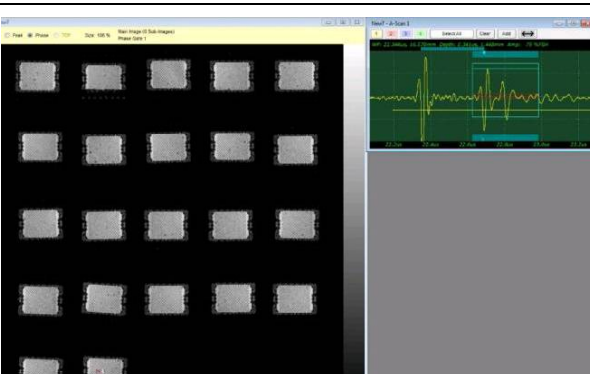


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## 6. ATTACHED FILE:

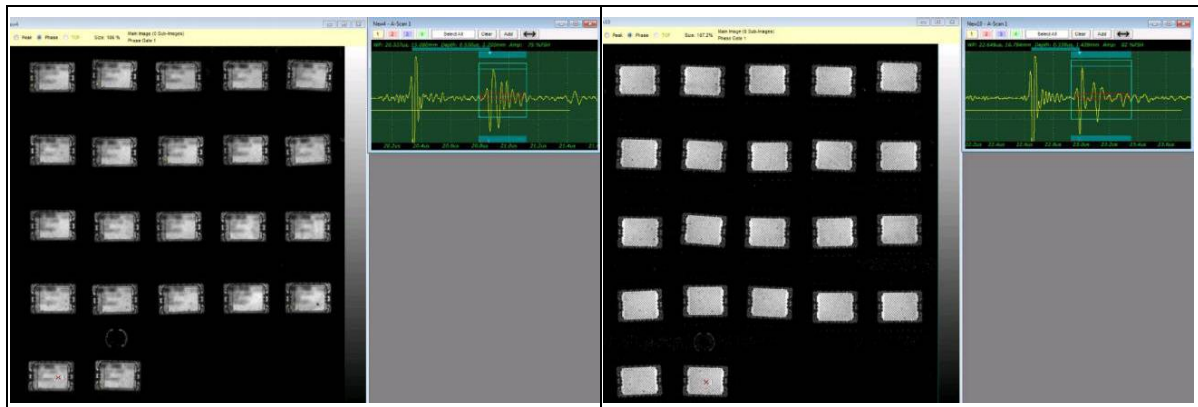
### 6-1. SAT PHOTO

#### 6-1-1. BEFORE PRE-CONDITION

<p>a1.Lot no# 8F806400BD: Topside of package</p> 	<p>a2.Lot no#8F806400BD: Backside of package</p> 
<p>b1.Lot no# 8F806400BH: Topside of package</p> 	<p>b2.Lot no# 8F806400BH: Backside of package</p> 
<p>c1.Lot no# 8F806400BK: Topside of package</p> 	<p>c2.Lot no#8F806400BK: Backside of package</p> 

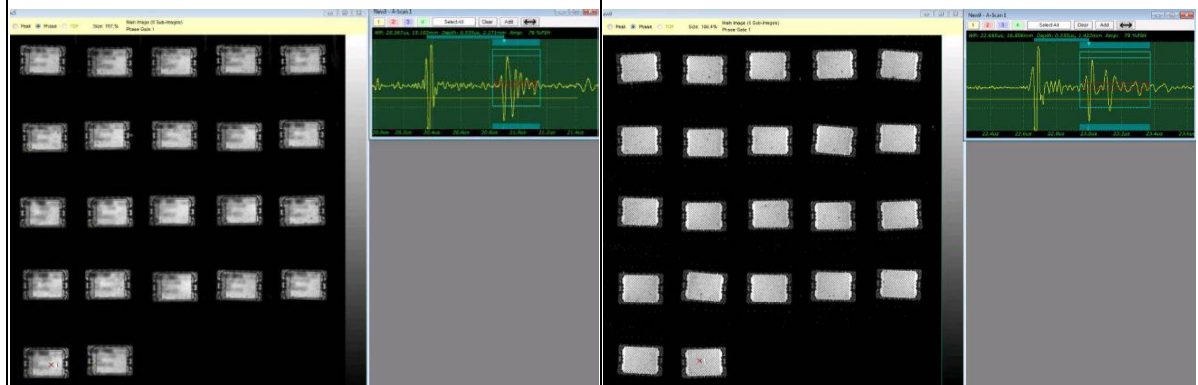
#### 6-1-2. AFTER PRE-CONDITION

a1.Lot no#8F806400BD: Topside of package	a2.Lot no# 8F806400BD: Backside of package
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b1.Lot no# 8F806400BH: Topside of package

b2.Lot no# 8F806400BH: Backside of package



c1.Lot no# 8F806400BK: Topside of package

c2.Lot no# 8F806400BK: Backside of package

